MA27V12

Silicon epitaxial planar type

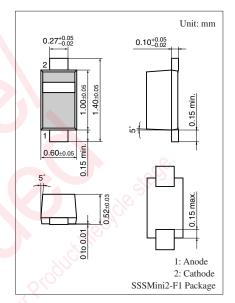
For VCO

■ Features

- \bullet Good linearity and large capacitance-ratio in $C_D V_R$ relation
- High frequency type by this low capacitance
- Ultraminiature Package 1.0 mm × 0.6 mm (height: 0.52 mm), optimum for high-density mounting and high-speed mounting

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	8	V
Junction temperature	T_{j}	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



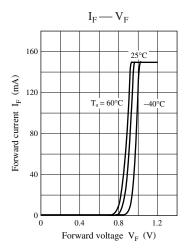
Marking Symbol: E

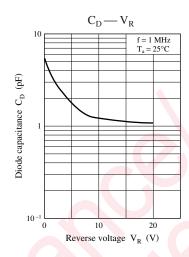
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

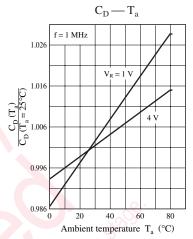
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Reverse current		I_R	$V_R = 5 \text{ V}$	1000	0,,	10	nA
Diode capacitance		$C_{D(1V)}$	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	3.60	0.	3.90	pF
		$C_{D(4V)}$	$V_R = 4 \text{ V, f} = 1 \text{ MHz}$	1.97		2.14	
Capacitance ratio		C _{D(1V)} /C _{D(4V)}	612 C. 110 1CC	1.75		1.90	_
Series resistance *	"Co.	r_{D}	$V_R = 4 \text{ V, f} = 470 \text{ MHz}$			0.35	Ω

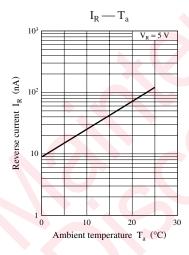
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 470 MHz.
- 3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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